RHS HF 157 Series – Standard Nano Fuse and Clip Assembly 🛛 🕬 🛚 🕸



Agency Approvals			
AGENCY	AGENCY FILE NUMBER	AMPERE RANGE	
c 🗣 us	E14721	0.062A ~ 10A	
PS	NBK030205-E10480A NBK030205-E10480B NBK101105-E184655	1A 1.5A - 5A 6.3A - 10A	

Electrical Characteristics for Series

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% of Ampere Rating	OpeningTime at 25°C
100%	4 hours Minimum
200%	5 secs. Maximum
10070	

Electrical Specifications by Item

Description

The 157 Series – Standard Nano Fuse/Clip assembly is a small, square, very fast acting surface mount fuse that is assembled in surface mountable fuse clips. The fuse clip and pre-installed fuse combination can be automatically placed in PC Board in one efficient manufacturing operation. It permits quick and easy replacement of fuses without performing desoldering process, even in the field and without exposing the PC Board to detrimental effects of rework solder heat.

Features

- Surface Mountable, Very Fast Acting Fuse.
- Fully compatible with RoHS/Pb-Free solder alloys and higher temperature profiles associated with leadfree assembly.
- Easily replaceable on PC Board (Field Replaceable)
- RoHS compliant and Halogen Free
 - Available in ratings of 0.062 ~ 10 Amperes.

Applications

- Instrumentation
- Base Stations
- Telecommunications

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Ampere Amp M		Max Voltage	Interrupting	Fuse	Nominal Cold	Nominal	Agency Approvals	
Rating (A)	Code	Rating (V)	Rating (A)	Furnished	Resistance (Ohms)	Melting I²t (A²sec)	c 🔁 us	PSE
0.062	.062	125		0451.062	5.5372	0.00019	Х	
0.080	.080	125		0451.080	4.0500	0.00033	X	
0.100	.100	125		0451.100	3.1000	0.00138	Х	
0.125	.125	125		0451.125	1.7059	0.00286	Х	
0.160	.160	125		0453.160	1.2157	0.0048	X	
0.200	.200	125		0453.200	1.3971	0.00652	X	
0.250	.250	125		0453.250	1.0496	0.01126	X	
0.315	.315	125		0453.315	0.3881	0.0311	X	
0.375	.375	125		0453.375	0.6083	0.0425	X	
0.400	.400	125		0453.400	0.5600	0.0484	X	
0.500	.500	125	50A @ 125 VAC/VDC	0453.500	0.4181	0.0795	X	
0.630	.630	125		0453.630	0.3050	0.143	X	
0.750	.750	125		0453.750	0.2458	0.185	X	
0.800	.800	125		0453.800	0.2120	0.271	X	
1.0	001.	125	2004 @ 221/00	0453001.	0.1537	0.459	X	Х
1.25	1.25	125	300A @ 32 VDC	04531.25	0.078	0.664	X	Х
1.5	01.5	125		045301.5	0.0634	0.853	X	Х
1.6	01.6	125		045301.6	0.0580	1.060	X	Х
2.0	002.	125		0453002.	0.0373	0.530	X	Х
2.5	02.5	125	·	045302.5	0.0288	1.029	X	Х
3.0	003.	125		0453003.	0.0229	1.650	X	Х
3.15	3.15	125		04533.15	0.0215	1.920	X	Х
3.5	03.5	125		045303.5	0.0203	2.469	X	Х
4.0	004.	125		0453004.	0.0163	3.152	X	Х
5.0	005.	125		0453005.	0.0127	5.566	X	Х
6.3	06.3	125		045306.3	0.0098	9.17	X	Х
7.0	007.	125		0453007.	0.0092	10.32	X	Х
8.0	008.	125	ľ	0453008.	0.0079	20.23	X	Х
10.0	010.	125	35A @ 125 VAC / 50A @125 VDC 300A @ 32VDC	0453010.	0.0058	26.46	X	Х

Cold resistance measured at less than 10% of rated current at 23°C.
 I²t values stated for 8ms opening time.

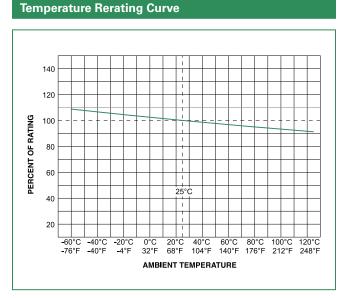
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Specifications are subject to change without notice. Please refer to www.littelfuse.com/series/157.html for current information. 157 Series

4. Have special electrical characteristic needs? Contact Littelfuse to learn more about application specific options.

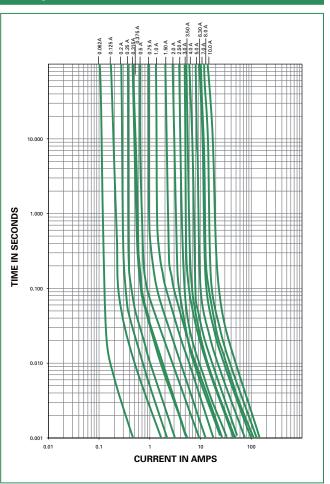
Surface Mount Fuses NANO^{2®} > 157 Fuse and Holder Combination

Average Time Current Curves



Note:

1. Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

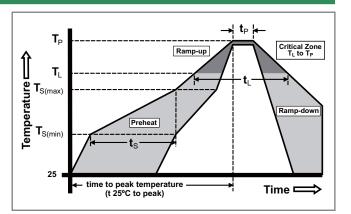


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Soldering Parameters

Reflow Co	ndition	Pb – Free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 120 secs	
Average ramp up rate (LiquidusTemp (T _L) to peak		5°C/second max.	
$T_{S(max)}$ to T_{L} - Ramp-up Rate		5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
	-Temperature (t _L)	60 – 90 seconds	
Peak Temperature (T _P)		250 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-down Rate		5°C/second max.	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	



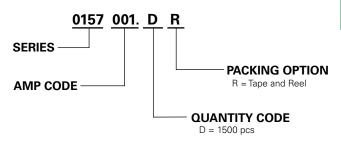


Product Characteristics

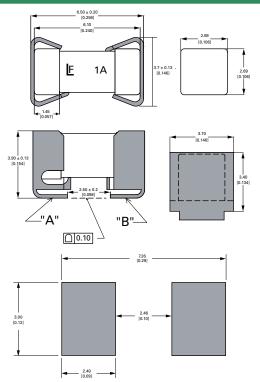
Materials	 Body: Ceramic Cap: For 0.062A ~ 0.125A – Au plated Brass For 0.200A ~ 10A – Silver plated Brass Clip Plating: Matte Tin 	
Product Marking	Body: Brand Logo, Current Rating	
Clip Retention	Force applied at fuse center, perpendicular to the long axis (@ 0.75 lbs. MIN)	
Solderability	MIL-STD-202, Method 208 / IPC/ EIA / JEDEC J-STD002B, Test Condition A	
Humidity Test	MIL –STD-202, Method 103 @ 85°C / 85%RH, 1000 hours	
Resistance to Solvents	MIL-STD-202, Method 215 (3 solvent types)	

Operating Temperature	-55°C to 125°C with proper derating	
Thermal Shock	MIL-STD-202, Method 107, Test Condition B (5 cycles -65°C to +125°C)	
Vibration	MIL-STD-202, Method 201 (10-55 Hz)	
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles	
Salt Spray/ Atmosphere	MILSTD-202, Method 101, Test Condition B (48 hrs.), 5% NaCl in De-ionized Water	
Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)	

Part Numbering System



Dimensions



PCB Recommendation for Thermal Management

Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed 80°C in a 25°C ambient environment.

Packaging					
Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code		
Tape and Reel	Surface Mount	1500	DR		

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Minimum Copper Layer Thickness = 100um
 Minimum Copper Trace Width = 10mm

Note:

